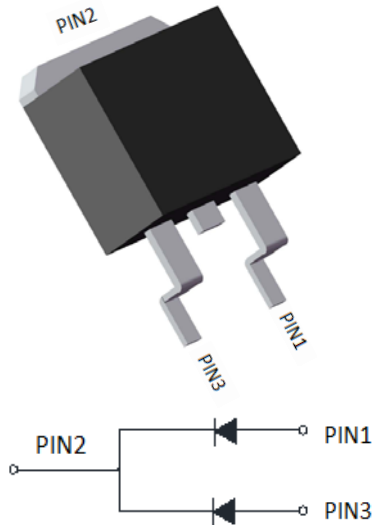


Schottky Diodes



Features

- High frequency operation
- Low forward voltage drop
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- Guard ring for enhanced ruggedness and long term reliability
- Solder dip 275 °C max. 7 s, per JESD 22-B106

Typical Applications

Typical applications are in switching power supplies, converters, freewheeling diodes, and reverse battery protection.

Mechanical Data

- **Package:** TO-263
Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant
- **Terminals:** Tin plated leads, solderable per J-STD-002 and JESD22-B102
- **Polarity:** As marked

■Maximum Ratings (T_a=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	MBRB20300CT
Device marking code			MBRB20300CT
Repetitive Peak Reverse Voltage	VRRM	V	300
Average Rectified Output Current @60Hz sine wave, R-load, T _a =25°C	I _O	A	20
Surge(Non-repetitive)Forward Current @60Hz half sine-wave, 1 cycle, T _a =25°C	I _{FSM}	A	200
Current Squared Time @1ms≤t<8.3ms T _j =25°C	I ² t	A ² s	167
Storage Temperature	T _{stg}	°C	-55 ~ +175
Junction Temperature	T _j	°C	-55 ~ +150

■Electrical Characteristics (T_a=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	TEST CONDITIONS	MBRB20300CT
Maximum instantaneous forward voltage drop per diode	V _{FM}	V	I _{FM} =10.0A	0.975
Maximum DC reverse current at rated DC blocking voltage per diode	I _{RRM1}	mA	V _{RM} =V _{RRM} T _a =25°C	0.05
	I _{RRM2}		V _{RM} =V _{RRM} T _a =100°C	10



MBRB20300CT

■ Thermal Characteristics (T_a=25°C Unless otherwise specified)

PARAMETER		SYMBOL	UNIT	MBRB20300CT
Thermal Resistance	Between junction and case	R _{θJ-C}	°CW	2.0

■ Ordering Information (Example)

PREFERED P/N	UNIT WEIGHT(g)	MINIIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
MBRB20300CT	Approximate 1.43	50	2000	8000	Tube
MBRB20300CT	Approximate 1.43	1000	2000	10000	Reel

■ Characteristics (Typical)

FIG1: I_o -T_c Curve

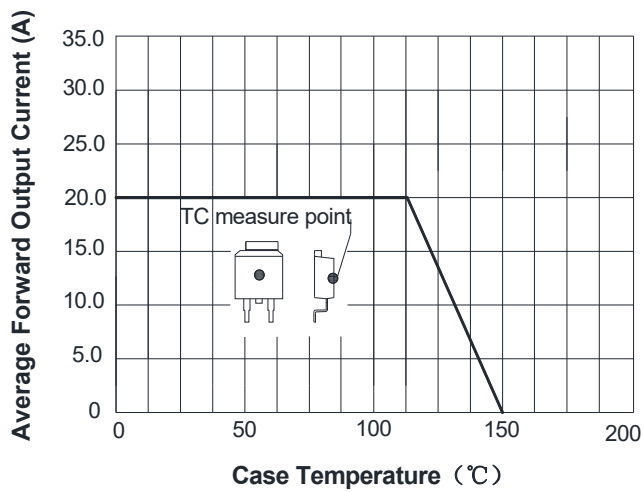


FIG2: Surge Forward Current Capability

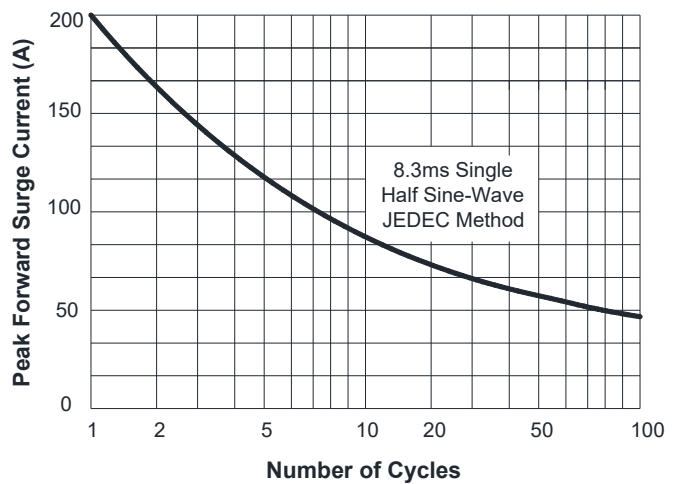


FIG3: Forward Voltage

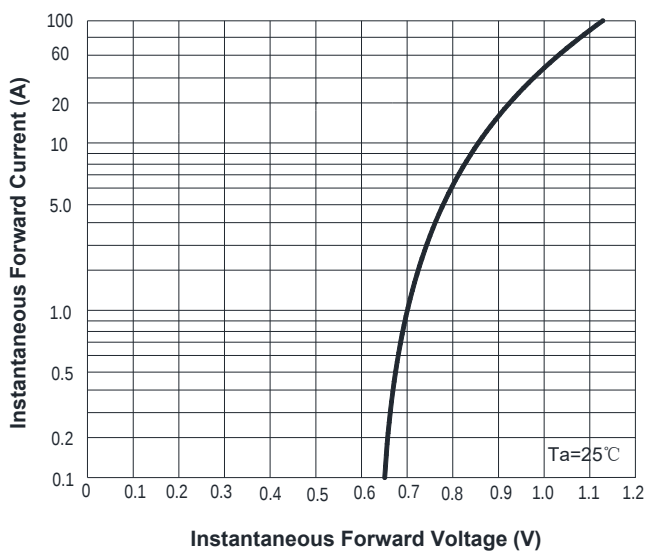
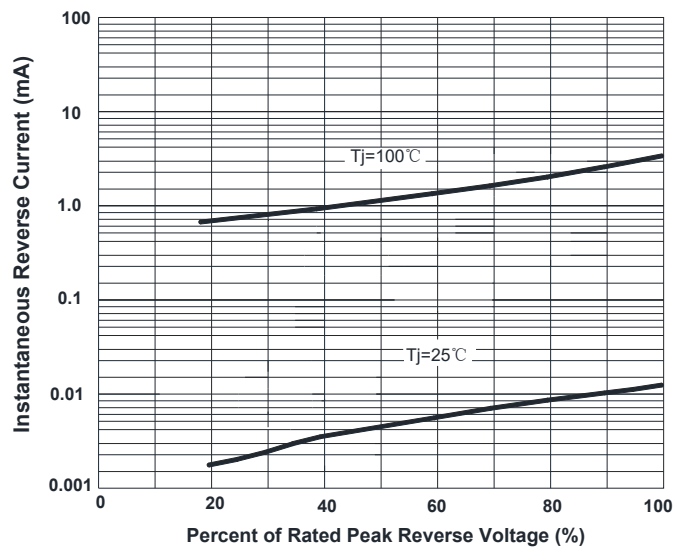
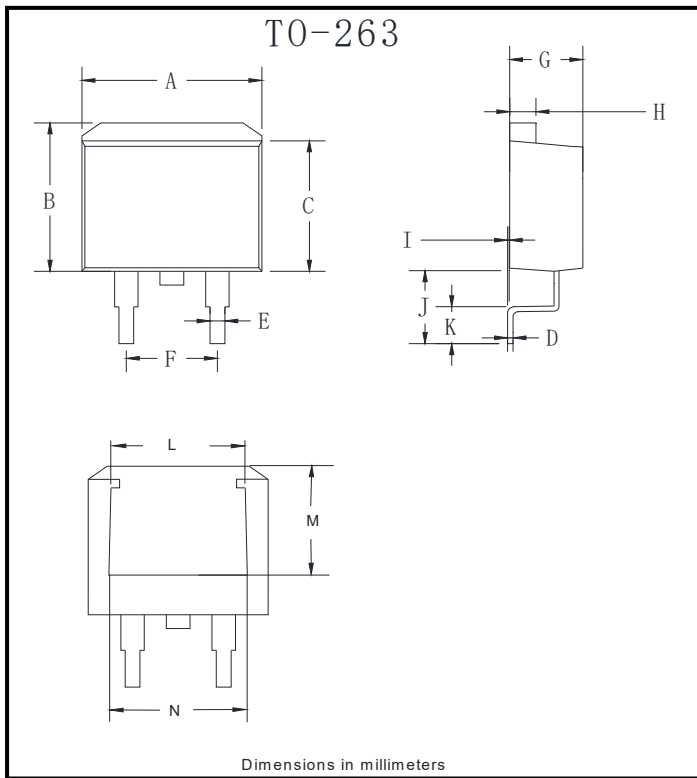


FIG.4: Typical Reverse Characteristics



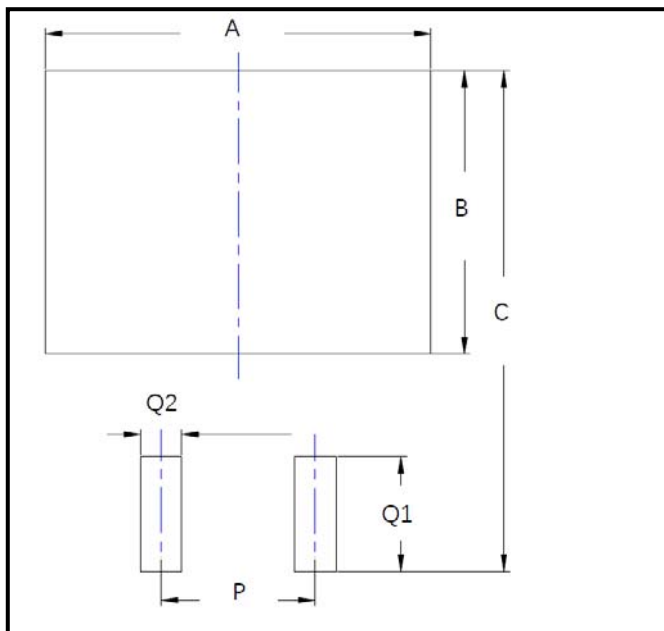


■Outline Dimensions



TO-263		
Dim	Min	Max
A	9.5	11.5
B	9.7	10.5
C	8.4	9.0
D	0.28	0.64
E	0.68	0.94
F	4.55	5.6
G	4.04	5.10
H	1.14	1.4
I	0	0.2
J	4.9	6.05
K	1.79	2.79
L	7.3	7.9
M	6.2	6.8
N	7.6	8.2

■Suggested Pad Layout



Dim	Millimeters
A	12.7
B	9.4
C	16.6
P	5.08
Q1	3.8
Q2	1.35



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